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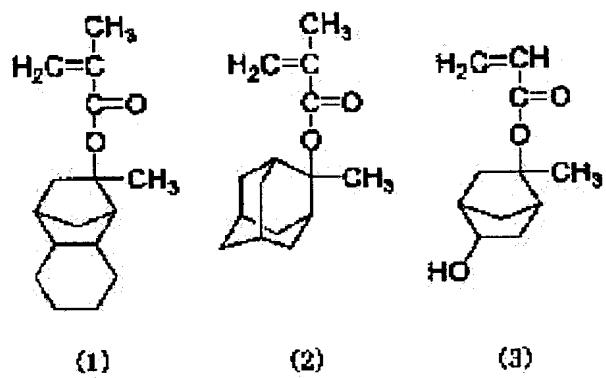
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(54) RADIATION SENSITIVE RESIN COMPOSITION

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a radiation sensitive resin composition having superior dry etching resistance and high transparency to radiation, excellent in basic physical properties as a resist such as sensitivity, resolution and pattern shape, excellent also in shelf stability as a composition and retaining satisfactory adhesiveness to a substrate.

SOLUTION: The radiation sensitive resin composition contains (A) a resin having repeating units derived from a derivative substituted by an oxygen-containing polar group (e.g. a hydroxyl or hydroxymethyl group) or a nitrogen-containing polar group (e.g. a cyano group), e.g. bicyclo[2.2.1]hept-2-ene or tetracyclo[4.4.0.12,5.17,10]dodec-3-ene, repeating units derived from maleic anhydride and repeating units derived from an acid dissociable ester derivative of (meth)acrylic acid typified by formula 1, 2 or 3 and (B) a radiation sensitive acid generating agent.



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